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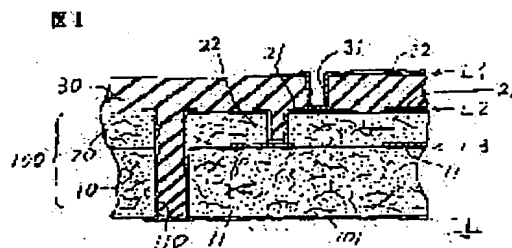
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(54) MULTILAYERED PRINTED WIRING BOARD AND METHOD OF MANUFACTURING LINE SIGNAL LINE THEREOF

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a multilayer printed wiring board and a method of manufacturing its line signal lines which is superior in elevating the packaging density of the wiring board and mechanical strength and manufactures them with a few steps at a low cost.

SOLUTION: The printed wiring board has a core board (100), formed by stacking a surface layer (20) on the surface of an inner board (10). At least a buildup layer (30) is formed on the surface of the core board, plating blind through-holes (22), for taking out line signal lines (11) formed on the inner board (10) surface are formed into the surface layer (20) of the core board, blind plating through-holes (31) for taking out line signal lines (21), formed on the surface of a surface layer of a core board (1100) are formed into the buildup layer (30), and only one buildup layer is stacked on the surface of the core board to form transmission lines L1-L3 of the three-layer structure.



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